

Ireland: Laboratory, optical and precision equipments (excl. glasses) LA3215C-UCC-CFT for the Supply of a Suite of Plasma Etcher and Plasma Deposition Tools, 4 Lots

Contract or concession notice – standard regime

1 Buyer

1.1 Buyer

Official name: Education Procurement Service (EPS)

Legal type of the buyer: Body governed by public law

Activity of the contracting authority: General public services

2 Procedure

2.1 Procedure

Title: LA3215C-UCC-CFT for the Supply of a Suite of Plasma Etcher and Plasma Deposition Tools, 4 Lots

Description: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Procedure identifier: a024c275-b92f-48d9-83b8-52aa370660c8

Type of procedure: Open

The procedure is accelerated: no

2.1.1 Purpose

Main nature of the contract: Supplies

Main classification (cpv): 38000000 Laboratory, optical and precision equipments (excl. glasses)

2.1.2 Place of performance

Country subdivision (NUTS): South-East (IE052)

Country: Ireland

2.1.3 Value

Estimated value excluding VAT: 3 300 000 Euro

2.1.4 General information

Legal basis:

Directive 2014/24/EU

2.1.5 Terms of procurement

Terms of submission:

Maximum number of lots for which one tenderer can submit tenders: 4

2.1.6 Grounds for exclusion

Sources of grounds for exclusion: Procurement Document

5 Lot

5.1 Lot: LOT-0001

Title: Plasma Etcher ,Silicon ,Dielectrics

Description: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Internal identifier: 1

5.1.1 Purpose

Main nature of the contract: Supplies

Main classification (cpv): 38000000 Laboratory, optical and precision equipments (excl. glasses)

5.1.2 Place of performance

Country subdivision (NUTS): South-East (IE052)

Country: Ireland

Additional information:

5.1.3 Estimated duration

Duration: 48 Month

5.1.5 Value

Estimated value excluding VAT: 3 300 000 Euro

5.1.6 General information

Reserved participation: Participation is not reserved.

Procurement Project not financed with EU Funds.

The procurement is covered by the Government Procurement Agreement (GPA): yes

5.1.7 Strategic procurement

Aim of strategic procurement: No strategic procurement

5.1.9 Selection criteria

Sources of selection criteria: Procurement Document

5.1.11 Procurement documents

Languages in which the procurement documents are officially available: English

Languages in which the procurement documents (or their parts) are unofficially available: English

Deadline for requesting additional information: 07/07/2026 12:00 +01:00

Address of the procurement documents: <https://www.etenders.gov.ie/epps/cft/listContractDocuments.do?resourceId=8424094>

5.1.12 Terms of procurement

Terms of submission:

Electronic submission: Required

Address for submission: <https://www.etenders.gov.ie/epps/cft/viewTenders.do?resourceId=8424094>

Languages in which tenders or requests to participate may be submitted: English

Electronic catalogue: Not allowed

Tenderers may submit more than one tender: Allowed

Deadline for receipt of tenders: 17/07/2026 12:00 +01:00

Duration during which the tender must remain valid: 180 Day

Information about public opening:

Opening date: 17/07/2026 12:30 +01:00

Place: <https://www.etenders.gov.ie/epps/cft/prepareViewCFTWS.do?resourceId=8424094>

Terms of contract:

The execution of the contract must be performed within the framework of sheltered employment programmes: Not yet known

Electronic invoicing: Required

Electronic ordering will be used: no

Electronic payment will be used: no

5.1.15 Techniques

Framework agreement:

No framework agreement

Information about the dynamic purchasing system:

No dynamic purchase system

5.1.16 Further information, mediation and review

Review organisation: The High Court of Ireland

Organisation providing offline access to the procurement documents: Education Procurement Service (EPS)

Organisation providing more information on the review procedures: The High Court of Ireland

Organisation receiving requests to participate: Education Procurement Service (EPS)

Organisation processing tenders: Education Procurement Service (EPS)

5.1 Lot: LOT-0002

Title: Plasma Etcher ,Metals ,Piezoelectrics

Description: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities

at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Internal identifier: 2

5.1.1 Purpose

Main nature of the contract: Supplies

Main classification (cpv): 38000000 Laboratory, optical and precision equipments (excl. glasses)

5.1.2 Place of performance

Country subdivision (NUTS): South-East (IE052)

Country: Ireland

Additional information:

5.1.3 Estimated duration

Duration: 48 Month

5.1.5 Value

Estimated value excluding VAT: 3 300 000 Euro

5.1.6 General information

Reserved participation: Participation is not reserved.

Procurement Project not financed with EU Funds.

The procurement is covered by the Government Procurement Agreement (GPA): yes

5.1.7 Strategic procurement

Aim of strategic procurement: No strategic procurement

5.1.9 Selection criteria

Sources of selection criteria: Procurement Document

5.1.11 Procurement documents

Languages in which the procurement documents are officially available: English

Languages in which the procurement documents (or their parts) are unofficially available: English

Deadline for requesting additional information: 07/07/2026 12:00 +01:00

Address of the procurement documents: <https://www.etenders.gov.ie/epps/cft/listContractDocuments.do?resourceId=8424094>

5.1.12 Terms of procurement

Terms of submission:

Electronic submission: Required

Address for submission: <https://www.etenders.gov.ie/epps/cft/viewTenders.do?resourceId=8424094>

Languages in which tenders or requests to participate may be submitted: English

Electronic catalogue: Not allowed

Tenderers may submit more than one tender: Allowed

Deadline for receipt of tenders: 17/07/2026 12:00 +01:00

Duration during which the tender must remain valid: 180 Day

Information about public opening:

Opening date: 17/07/2026 12:30 +01:00

Place: <https://www.etenders.gov.ie/epps/cft/prepareViewCfTWS.do?resourceId=8424094>

Terms of contract:

The execution of the contract must be performed within the framework of sheltered employment programmes: Not yet known

Electronic invoicing: Required

Electronic ordering will be used: no

Electronic payment will be used: no

5.1.15 Techniques

Framework agreement:

No framework agreement

Information about the dynamic purchasing system:

No dynamic purchase system

5.1.16 Further information, mediation and review

Review organisation: The High Court of Ireland

Organisation providing offline access to the procurement documents: Education Procurement Service (EPS)

Organisation providing more information on the review procedures: The High Court of Ireland

Organisation receiving requests to participate: Education Procurement Service (EPS)

Organisation processing tenders: Education Procurement Service (EPS)

5.1 Lot: LOT-0003

Title: Plasma Etcher ,Slow and Controllable Rate ,Atomic Layer Etch for Silicon , Dielectrics

Description: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Internal identifier: 3

5.1.1 Purpose

Main nature of the contract: Supplies

Main classification (cpv): 38000000 Laboratory, optical and precision equipments (excl. glasses)

5.1.2 Place of performance

Country subdivision (NUTS): South-East (IE052)

Country: Ireland

Additional information:

5.1.3 Estimated duration

Duration: 48 Month

5.1.5 Value

Estimated value excluding VAT: 3 300 000 Euro

5.1.6 General information

Reserved participation: Participation is not reserved.

Procurement Project not financed with EU Funds.

The procurement is covered by the Government Procurement Agreement (GPA): yes

5.1.7 Strategic procurement

Aim of strategic procurement: No strategic procurement

5.1.9 Selection criteria

Sources of selection criteria: Procurement Document

5.1.11 Procurement documents

Languages in which the procurement documents are officially available: English

Languages in which the procurement documents (or their parts) are unofficially available: English

Deadline for requesting additional information: 07/07/2026 12:00 +01:00

Address of the procurement documents: <https://www.etenders.gov.ie/epps/cft/listContractDocuments.do?resourceId=8424094>

5.1.12 Terms of procurement

Terms of submission:

Electronic submission: Required

Address for submission: <https://www.etenders.gov.ie/epps/cft/viewTenders.do?resourceId=8424094>

Languages in which tenders or requests to participate may be submitted: English

Electronic catalogue: Not allowed

Tenderers may submit more than one tender: Allowed

Deadline for receipt of tenders: 17/07/2026 12:00 +01:00

Duration during which the tender must remain valid: 180 Day

Information about public opening:

Opening date: 17/07/2026 12:30 +01:00

Place: <https://www.etenders.gov.ie/epps/cft/prepareViewCftWS.do?resourceId=8424094>

Terms of contract:

The execution of the contract must be performed within the framework of sheltered employment programmes: Not yet known

Electronic invoicing: Required

Electronic ordering will be used: no

Electronic payment will be used: no

5.1.15 Techniques

Framework agreement:

No framework agreement

Information about the dynamic purchasing system:

No dynamic purchase system

5.1.16 Further information, mediation and review

Review organisation: The High Court of Ireland

Organisation providing offline access to the procurement documents: Education Procurement Service (EPS)

Organisation providing more information on the review procedures: The High Court of Ireland

Organisation receiving requests to participate: Education Procurement Service (EPS)

Organisation processing tenders: Education Procurement Service (EPS)

5.1 Lot: LOT-0004

Title: Plasma Deposition ,PECVD

Description: Tenders are sought for the supply delivery, installation and commissioning of a suite of tools in 4 Lots for silicon-based and dielectric materials for University College Cork. The new plasma tools will enhance the capabilities at the Tyndall National Institute for the fabrication of semiconductor devices, especially silicon microelectronics and silicon MEMS, but also other materials such as germanium and silicon carbide. We invite proposals for the following lots; Lot 1 Plasma Etcher Silicon Dielectrics, advanced plasma etching system capable of etching for polysilicon poly-Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 2 Plasma Etcher Metals Piezoelectrics, advanced plasma etching system capable of etching for aluminium Al and alloys molybdenum Mo aluminium scandium nitride AlScN thin films using medium high-density plasma processes. Lot 3 Plasma Etcher Slow and Controllable Rate Atomic Layer Etch for Silicon Dielectrics, advanced plasma etching system capable of both conventional high-rate etching and slow and controllable rate atomic layer etching for silicon Si silicon dioxide SiO₂ silicon nitride SiN thin films using medium high-density plasma processes. Lot 4 Plasma Deposition PECVD, advanced plasma enhanced chemical vapour deposition system capable of depositing dielectric SiO₂, SiN and amorphous a-Si thin films on semiconductor substrates. This equipment will be essential for etching and depositing a range of materials used in the fabrication of silicon microelectronics, silicon photonics and silicon MEMS devices. The ideal tools will offer precision, reliability, and efficiency to meet the requirements for etching and deposition on both 100 mm and 200 mm diameter wafers. Tenderers with cutting-edge solutions that can achieve these high standards are encouraged to submit their proposals for this vital component in our technological advancement.

Internal identifier: 4

5.1.1 Purpose

Main nature of the contract: Supplies

Main classification (cpv): 38000000 Laboratory, optical and precision equipments (excl. glasses)

5.1.2 Place of performance

Country subdivision (NUTS): South-East (IE052)

Country: Ireland

Additional information:

5.1.3 Estimated duration

Duration: 48 Month

5.1.5 Value

Estimated value excluding VAT: 3 300 000 Euro

5.1.6 General information

Reserved participation: Participation is not reserved.

Procurement Project not financed with EU Funds.

The procurement is covered by the Government Procurement Agreement (GPA): yes

5.1.7 Strategic procurement

Aim of strategic procurement: No strategic procurement

5.1.9 Selection criteria

Sources of selection criteria: Procurement Document

5.1.11 Procurement documents

Languages in which the procurement documents are officially available: English

Languages in which the procurement documents (or their parts) are unofficially available: English

Deadline for requesting additional information: 07/07/2026 12:00 +01:00

Address of the procurement documents: <https://www.etenders.gov.ie/epps/cft/listContractDocuments.do?resourceId=8424094>

5.1.12 Terms of procurement

Terms of submission:

Electronic submission: Required

Address for submission: <https://www.etenders.gov.ie/epps/cft/viewTenders.do?resourceId=8424094>

Languages in which tenders or requests to participate may be submitted: English

Electronic catalogue: Not allowed

Tenderers may submit more than one tender: Allowed

Deadline for receipt of tenders: 17/07/2026 12:00 +01:00

Duration during which the tender must remain valid: 180 Day

Information about public opening:

Opening date: 17/07/2026 12:30 +01:00

Place: <https://www.etenders.gov.ie/epps/cft/prepareViewCFTWS.do?resourceId=8424094>

Terms of contract:

The execution of the contract must be performed within the framework of sheltered employment programmes: Not yet known

Electronic invoicing: Required

Electronic ordering will be used: no

Electronic payment will be used: no

5.1.15 Techniques

Framework agreement:

No framework agreement

Information about the dynamic purchasing system:

No dynamic purchase system

5.1.16 Further information, mediation and review

Review organisation: The High Court of Ireland

Organisation providing offline access to the procurement documents: Education Procurement Service (EPS)

Organisation providing more information on the review procedures: The High Court of Ireland

Organisation receiving requests to participate: Education Procurement Service (EPS)

Organisation processing tenders: Education Procurement Service (EPS)

8 Organisations

8.1 ORG-0001

Official name: Education Procurement Service (EPS)
Registration number: IE 6609370 G
Postal address: Castletroy Limerick
Town: Limerick
Postcode: V94 DK53
Country subdivision (NUTS): Mid-West (IE051)
Country: Ireland
Email: info@educationprocurementservice.ie
Telephone: 000
Internet address: <https://www.educationprocurementservice.ie/>
Buyer profile: <https://www.educationprocurementservice.ie/>
Roles of this organisation:

Buyer

Organisation providing offline access to the procurement documents

Organisation receiving requests to participate

Organisation processing tenders

8.1 ORG-0002

Official name: The High Court of Ireland
Registration number: The High Court of Ireland
Department: The High Court of Ireland
Postal address: Four Courts, Inns Quay, Dublin 7
Town: Dublin
Postcode: D07 WDX8
Country subdivision (NUTS): Dublin (IE061)
Country: Ireland
Email: HighCourtCentralOffice@courts.ie
Telephone: +353 1 8886000
Roles of this organisation:

Review organisation

Organisation providing more information on the review procedures

8.1 ORG-0003

Official name: European Dynamics S.A.
Registration number: 002024901000
Department: European Dynamics S.A.
Town: Athens
Postcode: 15125
Country subdivision (NUTS): Βόρειος Τομέας Αθηνών (EL301)
Country: Greece
Email: eproc-esender@eurodyn.com
Telephone: +30 2108094500
Roles of this organisation:

TED eSender

Notice information

Notice identifier/version: 46fee6a2-f409-4cd6-80db-618a50fcc925 - 01

Form type: Competition

Notice type: Contract or concession notice – standard regime

Notice dispatch date: 16/06/2026 13:47 +01:00

Languages in which this notice is officially available: English